

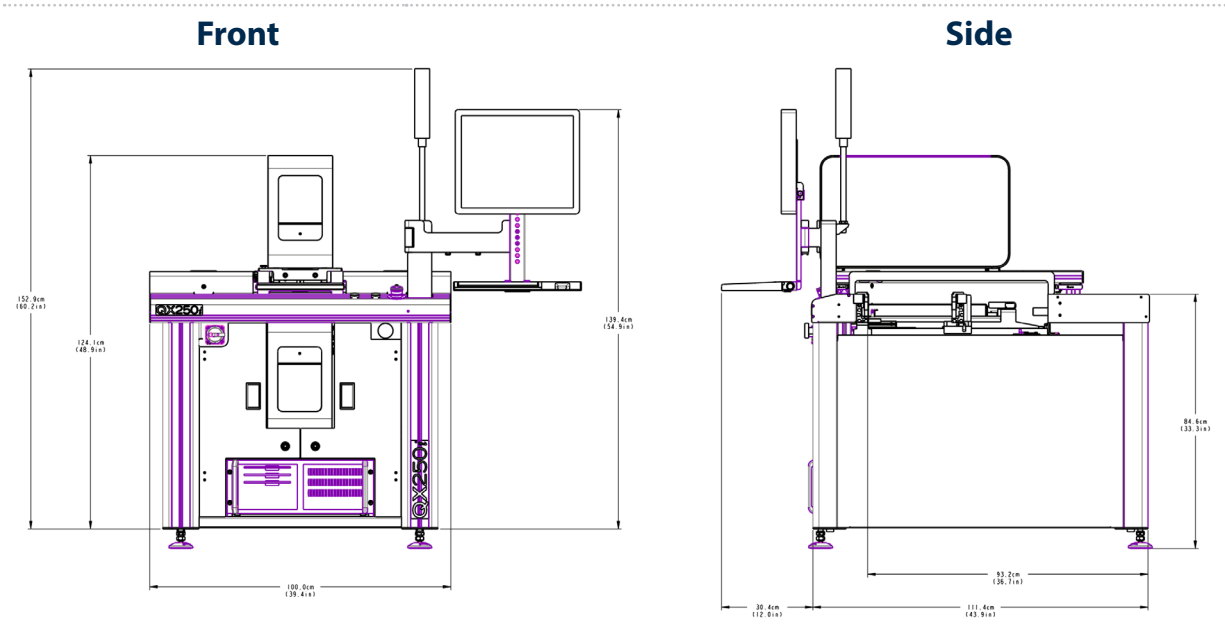
# QX250i™ 2D AOI

High Value, Flexible Inspection for All Applications

Inspection Capabilities	QX250i	QX200i
<b>Typical Scanning Speed</b>	110 cm <sup>2</sup> /sec	150 cm <sup>2</sup> /sec
<b>Minimum Component Size</b>	0402 mm (01005 in.)	
<b>Board Length</b>	Min. 50 mm (2 in.)/ Max. 405 mm (16 in.)	
<b>Board Width</b>	Min. 50 mm (2 in.)/ Max. 308 mm (12 in.)	
<b>Component Height Clearance (max)</b>	Top: 35 mm Bottom: 34mm	Top: 30 mm Bottom: 29 mm
<b>Board Edge Clearance (min)</b>	3.0 mm (0.125 in.) – bottom side only	
<b>Maximum Board Weight</b>	3kg	
<b>Maximum Board Warp</b>	Up to +/-7 mm	
<b>Component Types Inspected</b>	Standard SMT (chips, J-lead, gull-wing, BGA, etc.), through-hole, odd-form, clips, connectors, header pins, and others	
<b>Solder Joint Defects Categories</b>	Solder bridge, opens, lifted leads, wettability, excess and insufficient solder, debris, and others	
<b>Other Items Detected</b>	Gold-finger contamination, pin-in-hole, bent pins, debris, and many others	
<b>Component Position Categories</b>	Component X, Y position and Rotation	
Vision System		
<b>Imagers</b>	80 Megapixel Sensor on each SIM module	40 Megapixel Sensor on each SIM module
<b>Image Transfer Protocol</b>	PCIe	
<b>Lighting</b>	Strobe White Light (with dark/bright field)	
<b>Resolution</b>	12 µm pixel size	17 µm pixel size
<b>Image Processing</b>	Statistical Appearance Modeling (SAM™) Technology. Option: Autonomous Image Interpretation (AI <sup>2</sup> ) Technology	
<b>Programming</b>	Simple inline or offline	
<b>CAD Import</b>	Any column separated text file (Standard information required – ref. designator, XY, Angle, Part no.,)	
System Specifications		
<b>Conveyor Height</b>	Adjustable to 835 – 990 mm (33 – 39 in.)	
<b>Machine Interface</b>	SMEGA, RS232 and Ethernet	
<b>Power Requirements</b>	100-120V, 15 Amp max or 220-240V 10 Amp max, 50/69 Hz	
<b>System Dimensions</b>	100 x 104.7 x 124 cm	
<b>Weight</b>	249 kgs (548.951 lbs.)	
<b>Machine Installation</b>	<1 hour	
Options		
SPC Software, Offline Defect Rework Station, Sensor Alignment Target, Barcode Readers (1D/2D)		



Ideal for  
Selective Solder and  
Pre-Reflow Applications



Contact CyberOptics today for more information  
800.366.9131 or 763.542.5000 | CSsales@cyberoptics.com | www.cyberoptics.com



# QX250i™ Intelligent Sensing Technology

The SIM (Strobed Inspection Module) is the core engine behind every QX250i™ / QX200i™ system enabling 'on-the-fly' high performance inspection. Designed and manufactured exclusively by CyberOptics, the SIM is absolutely calibration-free and illuminates only when needed – reducing cost of ownership and power consumption.

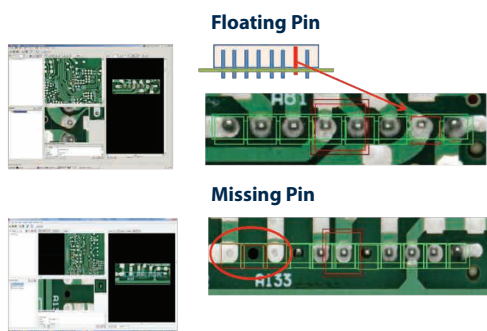
The dual top and bottom SIMs provide a single platform for the inspection and defect review process that shortens the production line and drives ~50% productivity improvement.



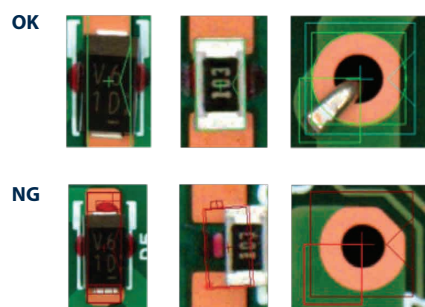
SIM (Strobe Inspection Module)

The SIM on the QX250i™ is designed with enhanced illumination – delivering the best 01005 and solder joint inspection performance ever. With an 80 Megapixel sensor and higher resolution (12 μm), you get crisp, perfect quality images for more accurate defect review. (The QX200i™ uses a 40 Megapixel sensor and to achieve a resolution of 17 μm.)

### Selective Soldering Inspection



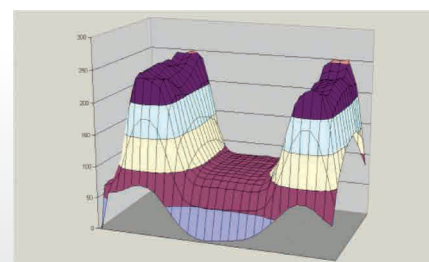
### Pre-Reflow Inspection



## Inspect 'Anything'

CyberOptics' AI<sup>2</sup> (Autonomous Image Interpretation) technology is designed for both low volume high mix, and high volume low mix Applications, and builds on the proven success of our Statistical Appearance Modeling technology. AI<sup>2</sup> is all about keeping it simple - no parameters to adjust or algorithms to tune. And, you don't need to anticipate defects or pre-define variance either – AI<sup>2</sup> does it all for you.

Just draw a box, show a few good examples and you are ready to inspect just about anything. Simply add good examples to the AI<sup>2</sup> model and the false call rates reduce significantly providing a very robust inspection solution.



AI<sup>2</sup> Software:  
Unique Image Processing Technique



Components Inspected/ Detected

## 3-Easy-Steps Programming

Our latest software improvements take programming to a whole, new level – zero to production ready in **less than 13 minutes!** All this is made possible, with an all-new data-rich, pre-loaded library and automated scripts that collect examples and update models – all on their own.

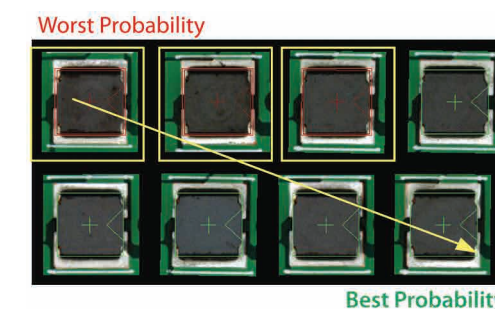


Simplified Programming Process

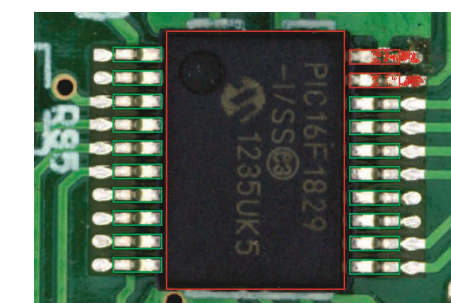
## AI<sup>2</sup> - Faster, Simpler, and Smarter

With AI<sup>2</sup> technology, programming gets even faster – with a 90% reduction in examples required to create a complete production ready programme – you will achieve superior defect detection and low false call rates even with just **one example**. This means significantly lower tuning time and quality results with one panel inspection. Perfect for those high-mix or low volume applications!

With its unique ability to 'ignore' bad examples in a model, AI<sup>2</sup> offers precise discrimination even with excessive variance and minimizes effects of outlier examples. Plus, it is a lot simpler with full support for unsupervised and semi-automatic model training. And, examples are pre-sorted so you can select and clear the ones you don't need – very quickly. The pixel marking feature highlights defective spots, so you can identify genuine defects instantly.



Intelligent Ranking of Examples



Active Pixel Marking

## Fast, Scalable SPC Solution

CyberReport™ offers full-fledged machine-level to factory-level SPC capability with powerful historical analysis and reporting tools delivering complete traceability for process verification and yield improvement. CyberReport™ is easy to setup and simple to use while providing fast charting with a compact database size.

